



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

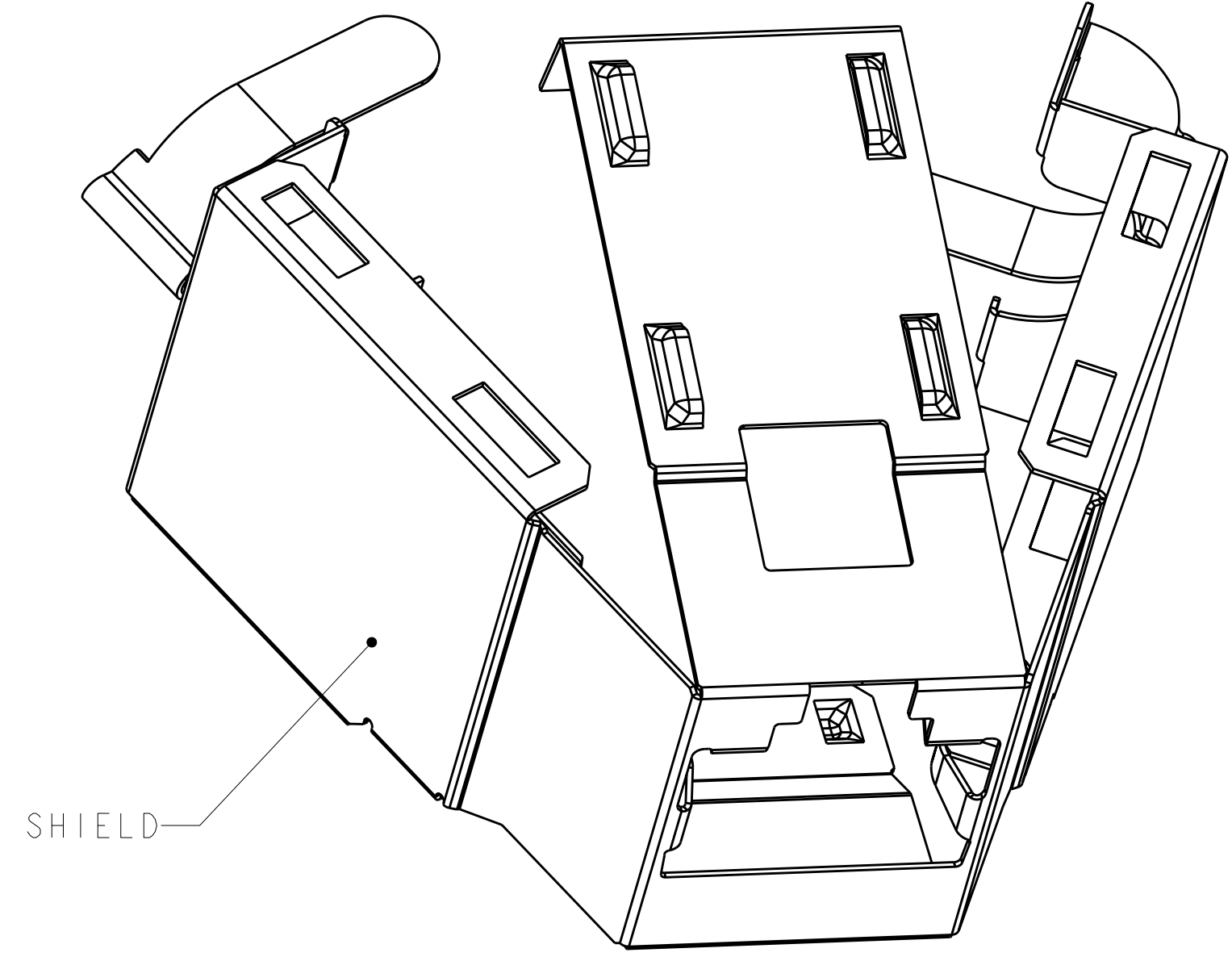
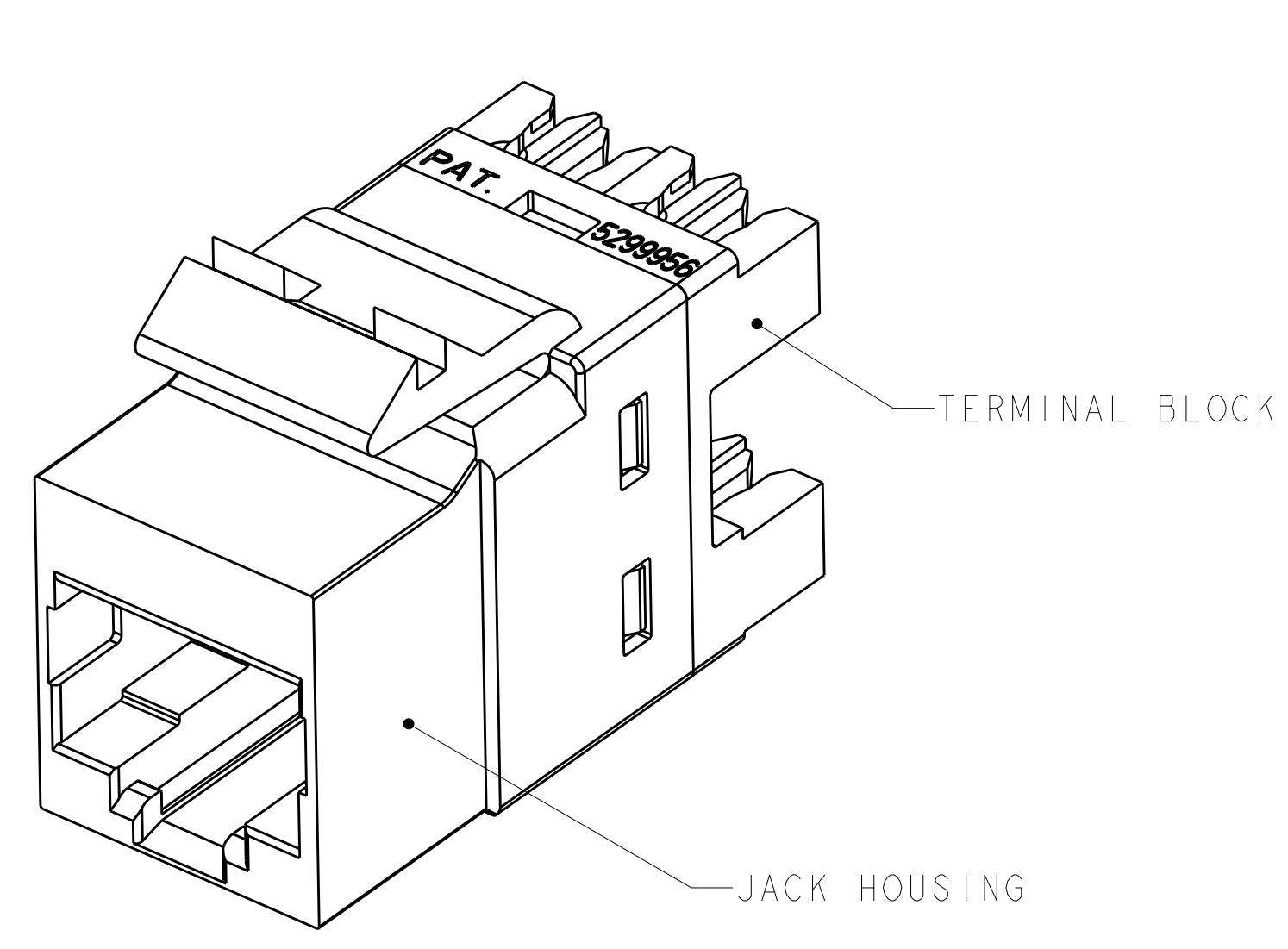
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

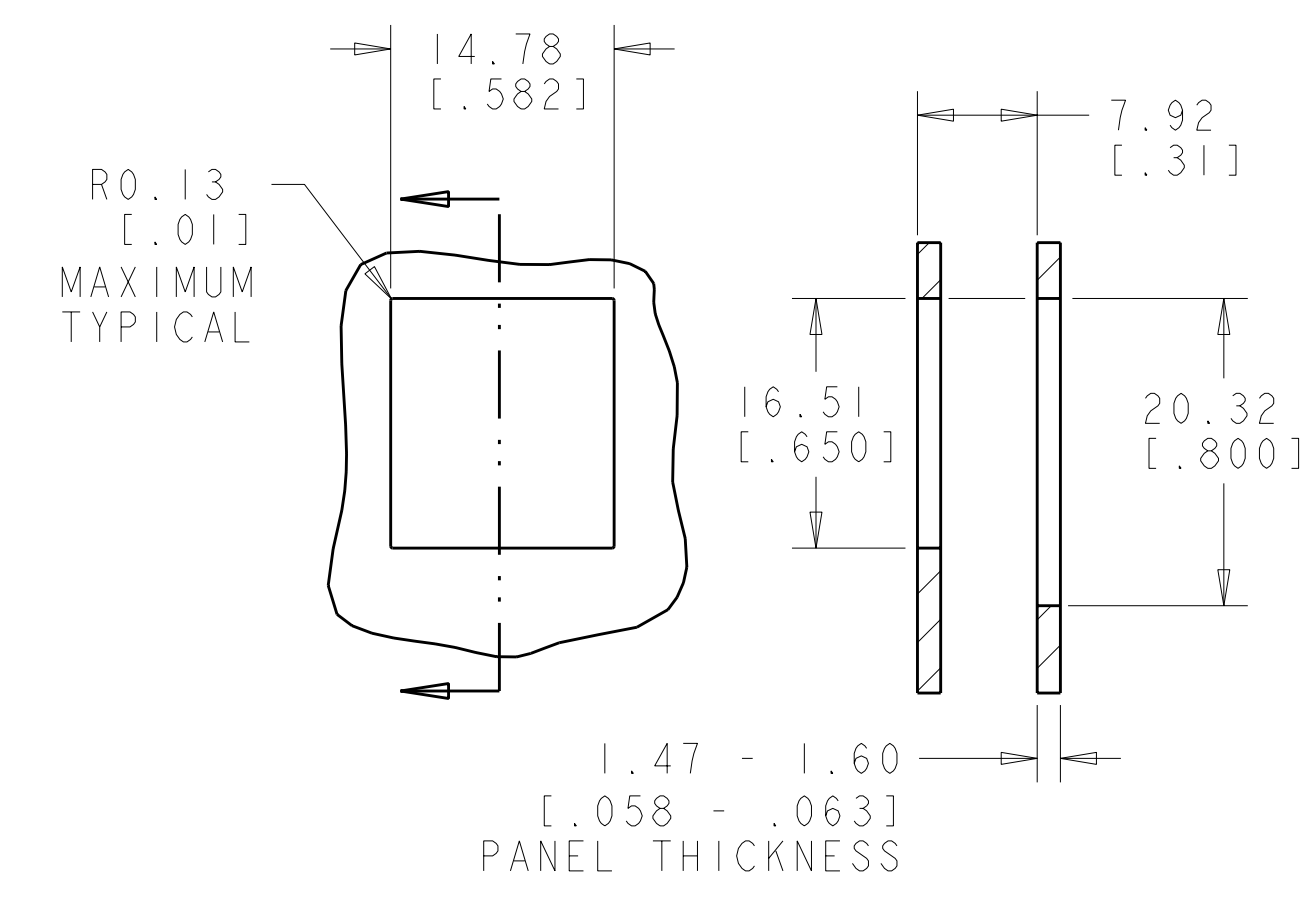
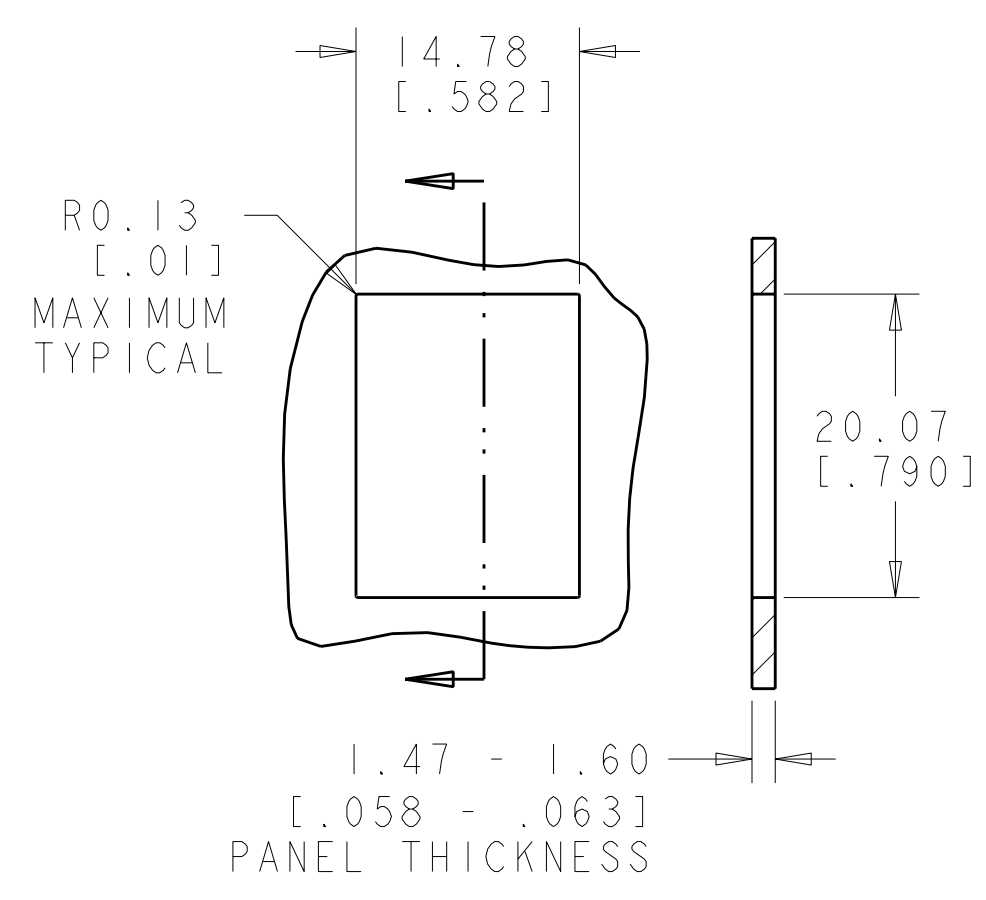
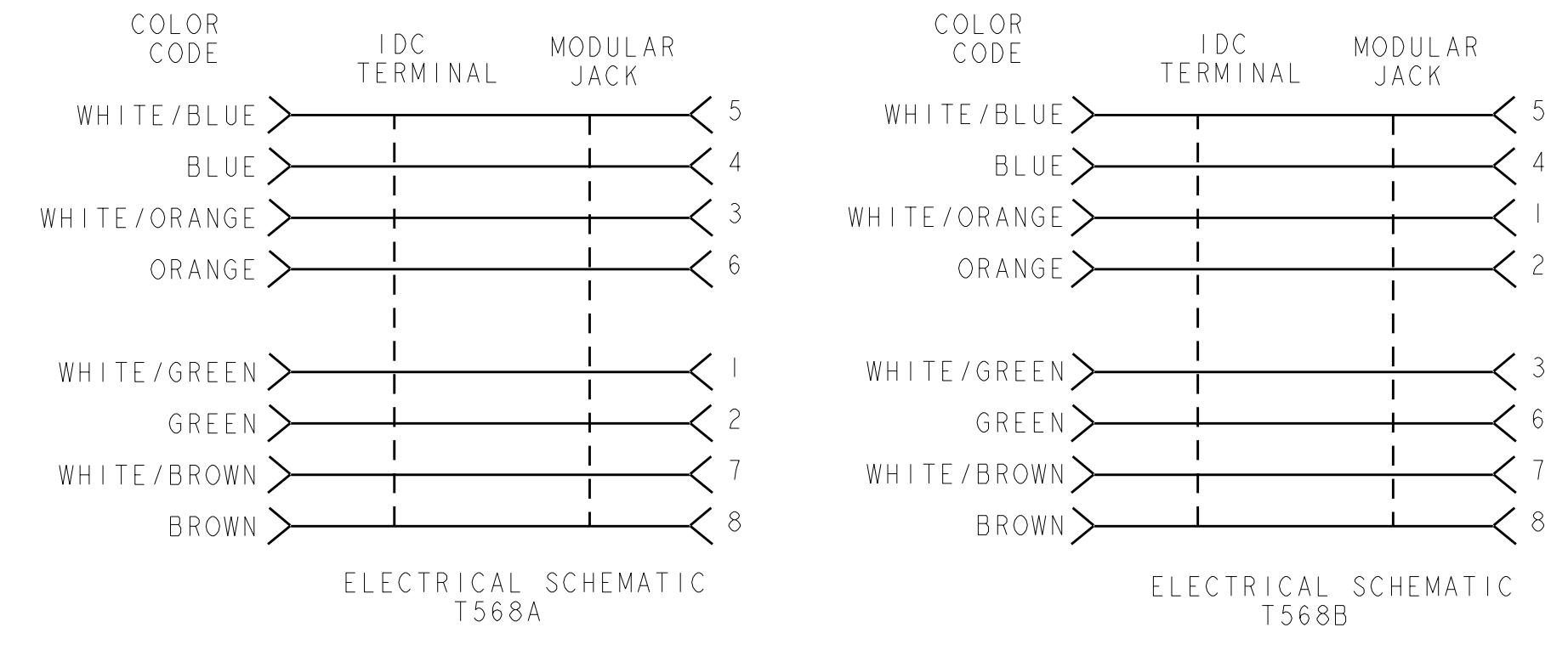
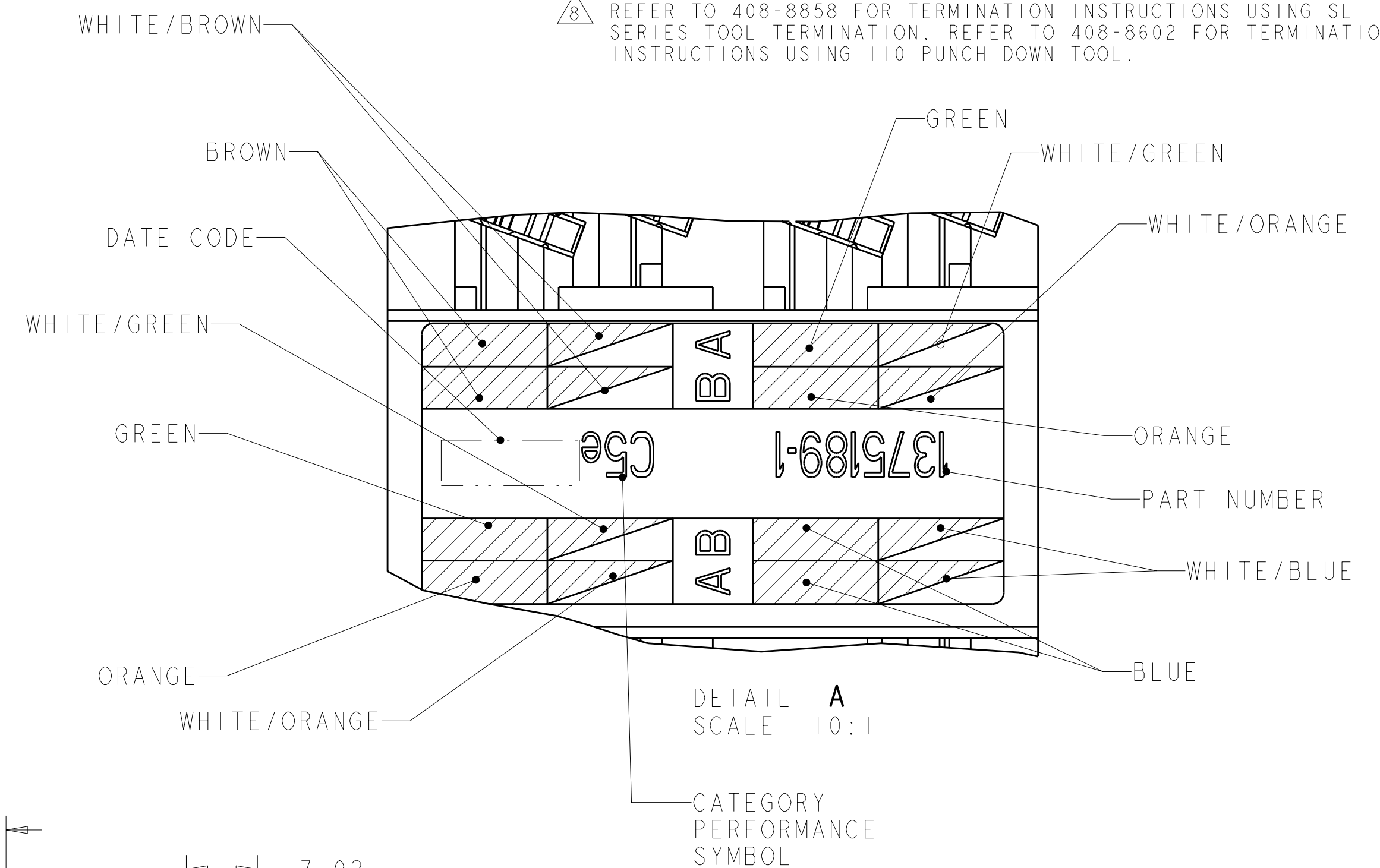
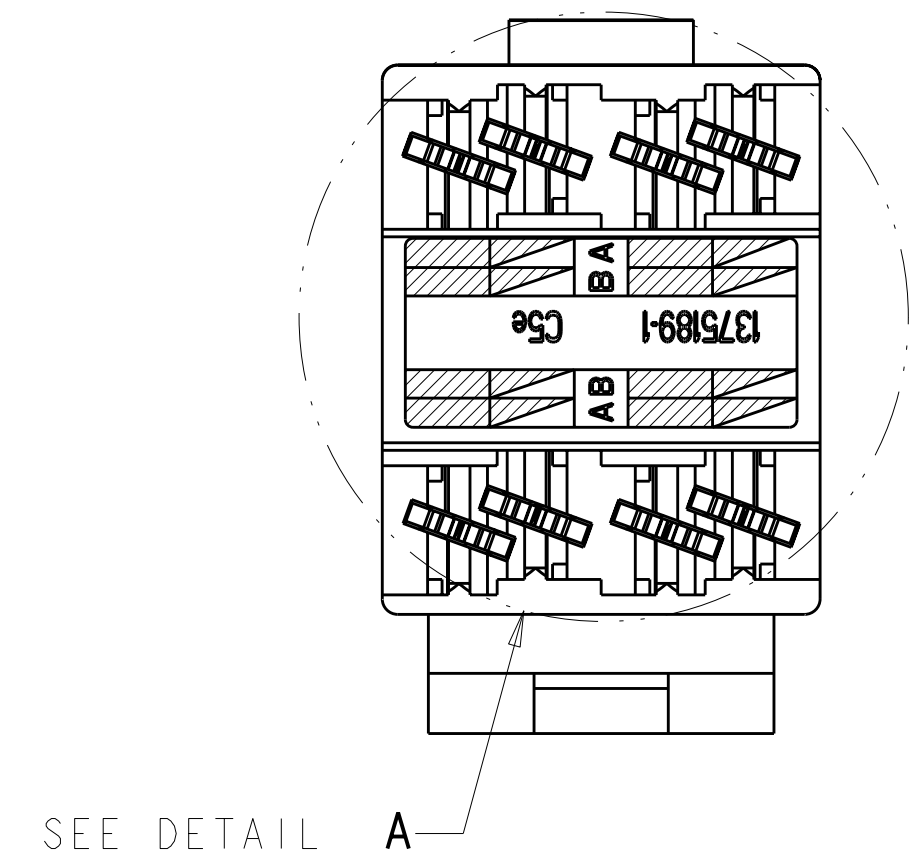
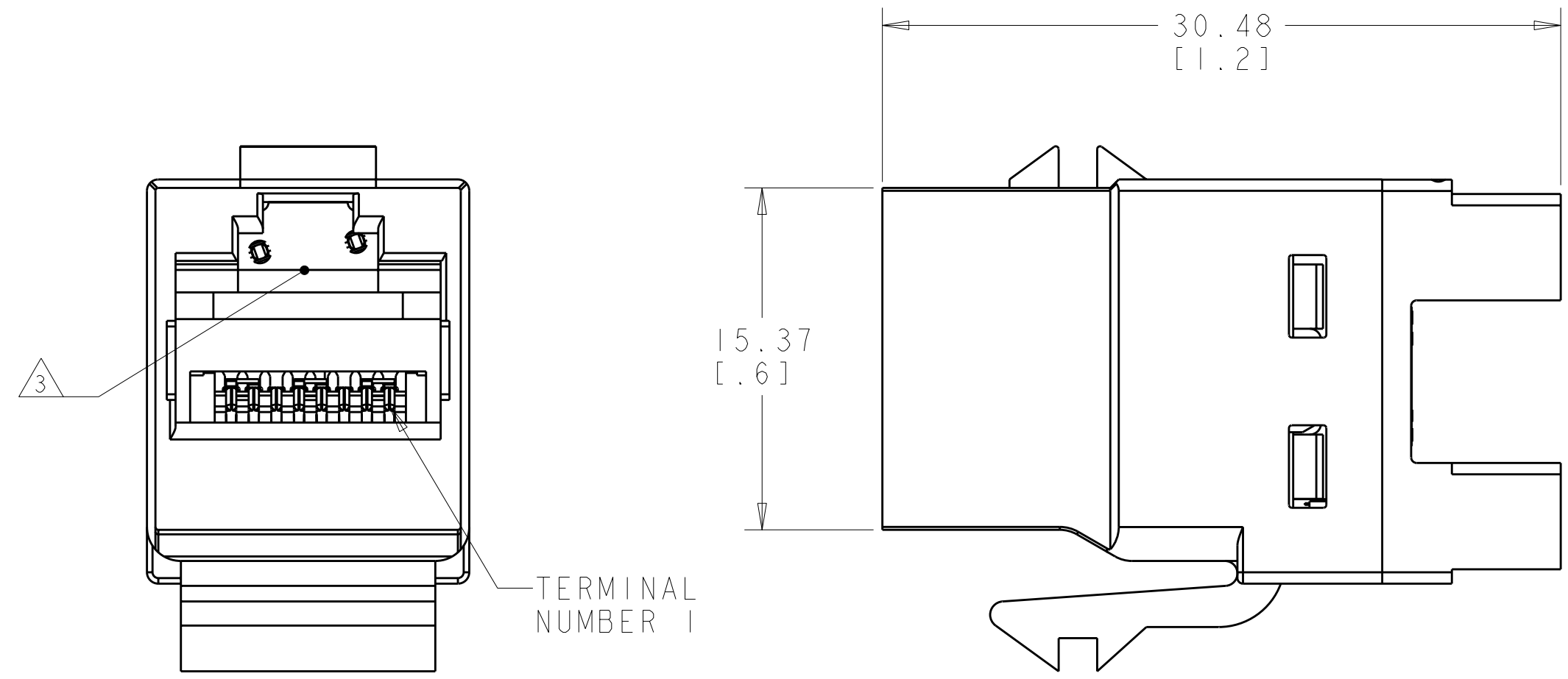
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



LOC	DIST	REV	DESCRIPTION	DATE	DWN	APVD
HM	00	H	REV: ECO-11-015895	06SEP2011	JB	SA



- 1. MATERIAL: JACK HOUSING - POLYCARBONATE, 94V-0 RATED.
 110 BLOCK - POLYCARBONATE.
 ARRAY TRAY - PBT POLYESTER.
 JACK CONTACTS ARRAY - BERYLLIUM COPPER, PLATED WITH 1.27µm [0.00050] MINIMUM THICK GOLD IN LOCALIZED AREA AND 3.81µm [0.00150] MINIMUM THICK MATTE TIN IN BOARD INTERFACE AREA OVER 1.27µm [0.00050] MINIMUM THICK NICKEL UNDERPLATE.
 SHIELD - COPPER ZINC ALLOY 260 PREPLATED WITH BRIGHT NICKEL.
 IDC TERMINALS - PHOSPHOROUS BRONZE, PLATED WITH 3.81µm [0.0015] MINIMUM THICK BRIGHT MATTE TIN OVER 1.27µm [0.0005] MINIMUM THICK NICKEL UNDERPLATE.
 SHIELD: COPPER ZINC ALLOY 260 PREPLATED WITH BRIGHT NICKEL.
- 2. SL 110 JACK WILL TERMINATE 22-24 AWG SOLID AND 24-26 AWG STRANDED CONDUCTORS, 1.27[.050] MAXIMUM INSULATION DIAMETER. JACK WILL ACCEPT CONDUCTORS UP TO 1.45 [.057] BUT REQUIRE THE USE OF A STRAIN RELIEF.
- 3. CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 SUBPART F REQUIREMENTS.
- 4. MOUNTING PANEL THICKNESS 1.47 - 1.60 [.058 - .063].
- 5. THESE TWO SUGGESTED CUTOUT OPENINGS ARE USED IN TANDEM WITH DUAL FRONT AND BACK CUTOUTS.
- 6. ONE MODULAR JACK ASSEMBLY AND ONE SHIELD PER POLYBAG.
- 7. SHIELD SHIPPED NOT ASSEMBLED.
- 8. REFER TO 408-8858 FOR TERMINATION INSTRUCTIONS USING SL SERIES TOOL TERMINATION. REFER TO 408-8602 FOR TERMINATION INSTRUCTIONS USING 110 PUNCH DOWN TOOL.



6	BLACK	1375189-1
PACKAGE	HOUSING COLOR	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: MM [inches]	TOLERANCES UNLESS OTHERWISE SPECIFIED:	9 PLC ±	1 PLC ±	2 PLC ±	3 PLC ±	4 PLC ±	ANGLES ±	FINISH
MATERIAL		WEIGHT		SIZE		CAGE CODE		DRAWING NO
CUSTOMER DRAWING		SCALE 4:1		SHEET 1 OF 1		REV H		RESTRICTED TO

STE TE Connectivity
 ASSEMBLY, SL 110 JACK, SHIELD, CATEGORY 5c
 A100779C-1375189